

Technical Data Sheet

SustaPEEK CF 30 - ASTM

PEEK

Typical characteristics

- Low coefficient of thermal expansion
- High rigidity
- High stiffness
- Good dimensional stability

Typical industries

- Electrical Industry
- Electronics
- Semiconductor Wafer Handling

	Test method	Unit	Guideline value
General properties			
Density	ASTM D792	g / cm ³	1.41
Water Absorption 24 hours	ASTM D570	%	0.06
Water Absorption Saturation	ASTM D570	%	0.3
Mechanical properties			
Hardness	ASTM D2240	Shore D	93
Tensile Strength at yield 73°F	ASTM D638	psi	20000
Tensile Modulus	ASTM D638	psi	1000000
Elongation at Break	ASTM D638	%	5
Flexural Strength	ASTM D790	psi	25000
Flexural Modulus	ASTM D790	psi	1300000
Compressive Strength	ASTM D695	psi	29000
Rockwell Hardness	ASTM D785		102
Rockwell Hardness	ASTM D785	R	124
Izod Impact, Notched	ASTM D256	ft-lb/in	1
Coefficient of Friction, Dynamic			0.2
Thermal properties			
Thermal Conductivity		in/hr/ft ² /°F	6.3
Coefficient of Linear Thermal Expansion	ASTM D696	in/in/°F x10 ⁻⁵	1
Melting Point	ASTM D789	°F	645
Continuous Service Temperature, Air		°F	480

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	Test method	Unit	Guideline value
Deflection Temperature at 1.8Mpa (264psi)	ASTM D648	°F	520
Flammability, UL94		1/8 inch	V-0
Electrical properties			
Dielectric constant	ASTM D150	1MHz	3.3
Dielectric strength	ASTM D149	V/mil	32
Surface resistivity	ASTM D257	Ω/cm	<10 ⁵
Compliance properties			
FDA			No
NSF			No
USDA			No

The data stated above are average values ascertained by statistical tests on a regular basis. The data above are provided purely for information and shall not be regarded as binding unless expressly agreed in a contract of sale.

